

Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

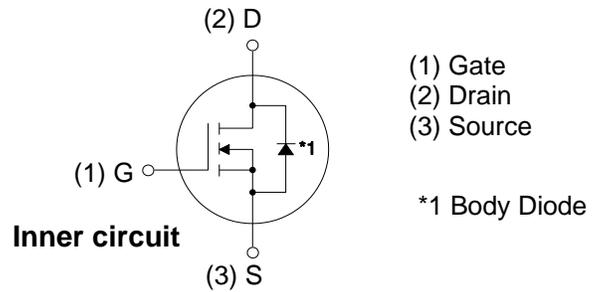
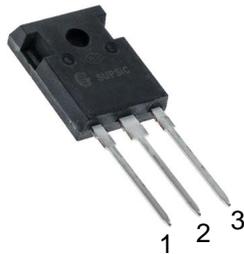
| Parameter | Rating | Units |
|--------------------------|------------|------------|
| V_{DS} | 650 | V |
| $I_D @ 25^\circ\text{C}$ | 122 | A |
| $R_{DS(on)}$ | 15 | m Ω |



Applications

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating

TO-247-3
Package



Maximum Ratings ($T_c=25^\circ\text{C}$, unless otherwise specified)

| Symbol | Parameter | Value | Unit | Note |
|----------------|--|-------------|------------------|------|
| V_{DSmax} | Drain - Source Voltage | 650 | V | |
| V_{GSmax} | Gate - Source voltage | -8/+19 | V | |
| I_D | Continuous Drain Current, $V_{GS} = 15\text{ V}$, $T_c = 25^\circ\text{C}$ | 122 | A | |
| | Continuous Drain Current, $V_{GS} = 15\text{ V}$, $T_c = 100^\circ\text{C}$ | 98 | | |
| $I_{D(pulse)}$ | Pulsed Drain Current, Pulse width t_p limited by T_{jmax} | 430 | A | |
| P_D | Power Dissipation, $T_c=25^\circ\text{C}$, $T_j = 175^\circ\text{C}$ | 420 | W | |
| T_j, T_{stg} | Operating Junction and Storage Temperature | -40 to +175 | $^\circ\text{C}$ | |
| T_L | Solder Temperature, 1.6mm (0.063") from case for 10s | 260 | $^\circ\text{C}$ | |
| M_d | Mounting Torque, (M3 or 6-32 screw) | 1 | Nm | |
| | | 8.8 | | |

Note (1): Recommended turn off / turn on gate voltage $V_{GS} = -4V \dots 0V / +15V$

Note (2): Package limited to 120 A

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Min. | Typ. | Max. | Unit | Test Conditions | Note |
|--------------|---|------|------|------|---------------|--|---------------|
| V_{BRIDSS} | Drain-Source Breakdown Voltage | 650 | | | V | $V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$ | |
| $V_{GS(th)}$ | Gate Threshold Voltage | 1.8 | 2.3 | 3.6 | V | $V_{DS} = V_{GS}, I_D = 15.5\ \text{mA}$ | |
| | | | 1.9 | | V | $V_{DS} = V_{GS}, I_D = 15.5\ \text{mA}, T_J = 175^\circ\text{C}$ | |
| I_{DSS} | Zero Gate Voltage Drain Current | | 1 | 50 | μA | $V_{DS} = 650\ \text{V}, V_{GS} = 0\ \text{V}$ | |
| I_{GSS} | Gate-Source Leakage Current | | 10 | 255 | nA | $V_{GS} = 15\ \text{V}, V_{DS} = 0\ \text{V}$ | |
| $R_{DS(on)}$ | Drain-Source On-State Resistance | 10.5 | 15 | 21 | m Ω | $V_{GS} = 15\ \text{V}, I_D = 55.8\ \text{A}$ | |
| | | | 20 | | | $V_{GS} = 15\ \text{V}, I_D = 55.8\ \text{A}, T_J = 175^\circ\text{C}$ | |
| g_{fs} | Transconductance | | 42 | | S | $V_{DS} = 20\ \text{V}, I_{DS} = 55.8\ \text{A}$ | |
| | | | 40 | | | $V_{DS} = 20\ \text{V}, I_{DS} = 55.8\ \text{A}, T_J = 175^\circ\text{C}$ | |
| C_{iss} | Input Capacitance | | 4960 | | pF | $V_{GS} = 0\ \text{V}, V_{DS} = 400\ \text{V}$ $f = 100\ \text{KHz}$ $V_{AC} = 25\ \text{mV}$ | |
| C_{oss} | Output Capacitance | | 290 | | | | |
| C_{rss} | Reverse Transfer Capacitance | | 31 | | | | |
| $C_{o(er)}$ | Effective Output Capacitance (Energy Related) | | 353 | | | | |
| $C_{o(tr)}$ | Effective Output Capacitance (Time Related) | | 516 | | | | |
| E_{oss} | C_{oss} Stored Energy | | 29 | | | | μJ |
| E_{ON} | Turn-On Switching Energy (Body Diode) | | 1500 | | μJ | $V_{DS} = 400\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}, I_D = 55.8\ \text{A},$ $R_{G(ext)} = 5\ \Omega, L = 57.6\ \mu\text{H}, T_J = 175^\circ\text{C}$ FWD = Internal Body Diode of MOSFET | |
| E_{OFF} | Turn Off Switching Energy (Body Diode) | | 710 | | | | |
| E_{ON} | Turn-On Switching Energy (External Diode) | | 1200 | | μJ | $V_{DS} = 400\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}, I_D = 55.8\ \text{A},$ $R_{G(ext)} = 5\ \Omega, L = 57.6\ \mu\text{H}, T_J = 175^\circ\text{C}$ FWD = External SiC DIODE | |
| E_{OFF} | Turn Off Switching Energy (External Diode) | | 1000 | | | | |
| $t_{d(on)}$ | Turn-On Delay Time | | 22 | | ns | $V_{DD} = 400\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}$ $I_D = 55.8\ \text{A}, R_{G(ext)} = 5\ \Omega, L = 57.6\ \mu\text{H}$ Timing relative to V_{DS} Inductive load | |
| t_r | Rise Time | | 128 | | | | |
| $t_{d(off)}$ | Turn-Off Delay Time | | 60 | | | | |
| t_f | Fall Time | | 25 | | | | |
| $R_{G(int)}$ | Internal Gate Resistance | | 1.5 | | Ω | $f = 1\ \text{MHz}, V_{AC} = 25\ \text{mV}$ | |
| Q_{gs} | Gate to Source Charge | | 54 | | nC | $V_{DS} = 400\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}$ $I_D = 55.8\ \text{A}$ Per IEC60747-8-4 pg 21 | |
| Q_{gd} | Gate to Drain Charge | | 62 | | | | |
| Q_g | Total Gate Charge | | 190 | | | | |

Note (3): $C_{o(er)}$, a lumped capacitance that gives same stored energy as C_{oss} while V_{ds} is rising from 0 to 400V
 $C_{o(tr)}$, a lumped capacitance that gives same charging time as C_{oss} while V_{ds} is rising from 0 to 400V

Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

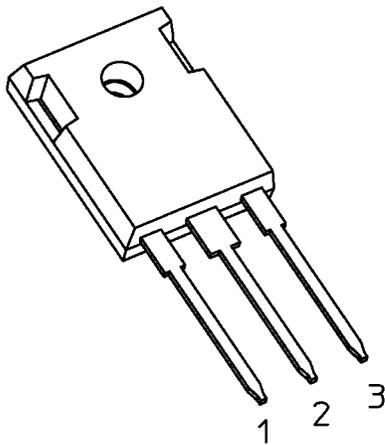
| Symbol | Parameter | Typ. | Max. | Unit | Test Conditions | Note |
|---------------|----------------------------------|------|------|------|---|------|
| V_{SD} | Diode Forward Voltage | 4.7 | | V | $V_{GS} = -4\text{ V}, I_{SD} = 27.9\text{ A}, T_J = 25^\circ\text{C}$ | |
| | | 4.2 | | V | $V_{GS} = -4\text{ V}, I_{SD} = 27.9\text{ A}, T_J = 175^\circ\text{C}$ | |
| I_S | Continuous Diode Forward Current | | 80 | A | $V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$ | |
| $I_{S,pulse}$ | Diode pulse Current | | 420 | A | $V_{GS} = -4\text{ V}$, pulse width t_p limited by T_{jmax} | |
| t_{rr} | Reverse Recovery time | 85 | | ns | $V_{GS} = -4\text{ V}, I_{SD} = 55.8\text{ A}, V_R = 400\text{ V}$ $dif/dt = 1500\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$ | |
| Q_{rr} | Reverse Recovery Charge | 670 | | nC | | |
| I_{rrm} | Peak Reverse Recovery Current | 17 | | A | | |
| t_{rr} | Reverse Recovery time | 74 | | ns | $V_{GS} = -4\text{ V}, I_{SD} = 55.8\text{ A}, V_R = 400\text{ V}$ $dif/dt = 1000\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$ | |
| Q_{rr} | Reverse Recovery Charge | 580 | | nC | | |
| I_{rrm} | Peak Reverse Recovery Current | 14 | | A | | |

Thermal Characteristics

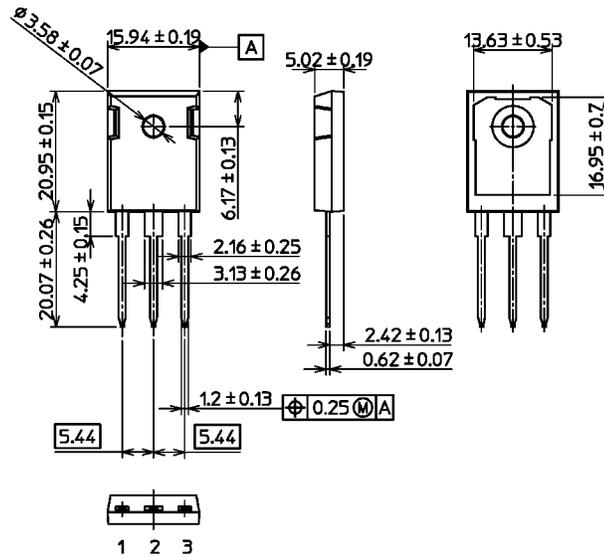
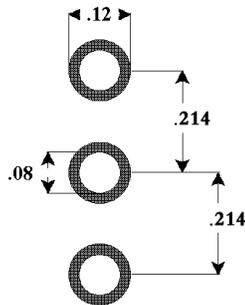
| Symbol | Parameter | Typ. | Unit | Test Conditions | Note |
|-----------------|---|------|---------------------------|-----------------|------|
| $R_{\theta JC}$ | Thermal Resistance from Junction to Case | 0.35 | $^\circ\text{C}/\text{W}$ | | |
| $R_{\theta JA}$ | Thermal Resistance From Junction to Ambient | 40 | | | |

Package Dimensions

Unit: mm



TO-247-3


Recommended Solder Pad Layout


TO-247-3